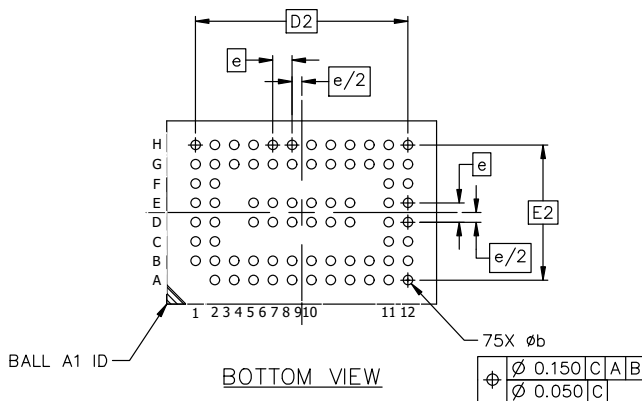
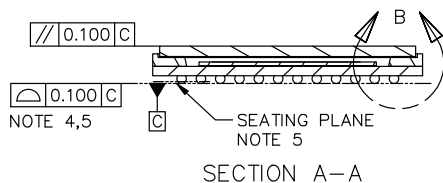
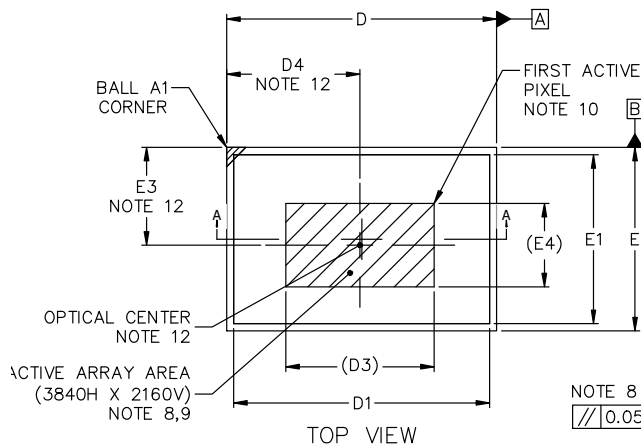
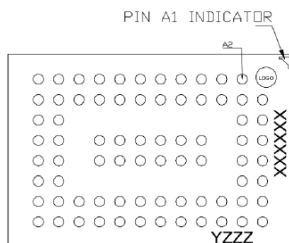


PBGA75 14.00x9.50x1.55, 1.00P  
CASE 117CU  
ISSUE A

DATE 18 JAN 2024



GENERIC  
MARKING DIAGRAM\*

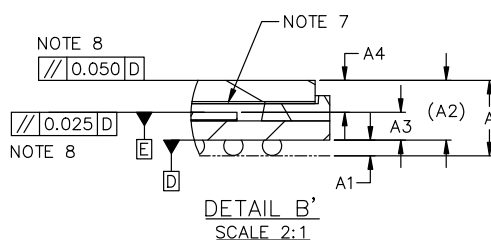


XXXX = Specific Device Code  
Y = Year  
ZZZ = Lot Traceability

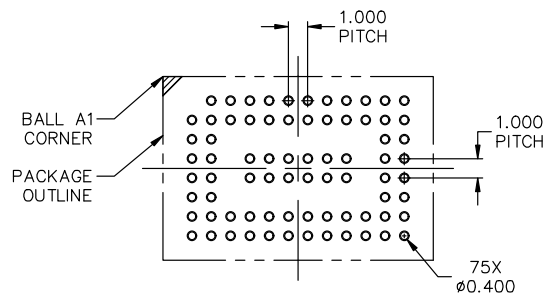
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

- DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- GLASS: 0.550 THICKNESS; REFRACTIVE INDEX = 1.52.
- AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.275 THICKNESS.
- PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
- MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS  $\pm 1^\circ$ .
- REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
- PACKAGE CENTER (X, Y) = (0.000, 0.000).
- OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.087, -0.315).



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	----	----	2.100
A1	0.350	0.400	0.450
A2	1.550 REF.		
A3	0.625	0.725	0.825
A4	0.725	0.825	0.925
b	0.450	0.500	0.550
D	13.900	14.000	14.100
D1	13.146	13.246	13.346
D2	11.000 BSC		
D3	7.680 REF.		
D4	6.813	6.913	7.013
E	9.400	9.500	9.600
E1	8.645	8.745	8.845
E2	7.000 BSC		
E3	4.965	5.065	5.165
E4	4.320 REF.		
e	1.000 BSC		



\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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